

# SN54ALS244C, SN54AS244A, SN74ALS244C, SN74AS244A OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SDAS142C – JULY 1987 – REVISED AUGUST 1995

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- pnp Inputs Reduce dc Loading
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

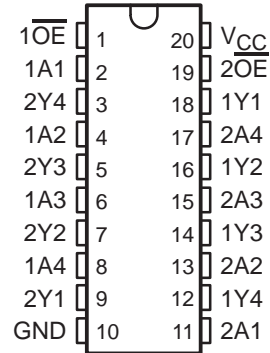
## description

These octal buffers and line drivers are designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. With the 'ALS240A, 'ALS241C, 'AS240A, and 'AS241A, these devices provide the choice of selected combinations of inverting outputs, symmetrical active-low output-enable ( $\overline{OE}$ ) inputs, and complementary OE and  $\overline{OE}$  inputs.

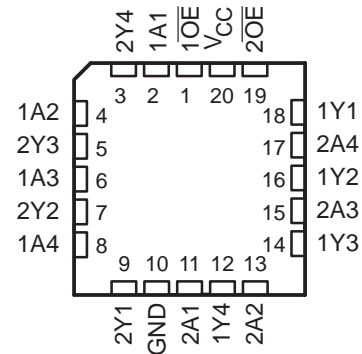
The -1 version of SN74ALS244C is identical to the standard version, except that the recommended maximum  $I_{OL}$  for the -1 version is 48 mA. There is no -1 version of the SN54ALS244C.

The SN54ALS244C and SN54AS244A are characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74ALS244C and SN74AS244A are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

SN54ALS244C, SN54AS244A . . . J PACKAGE  
SN74ALS244C, SN74AS244A . . . DW OR N PACKAGE  
(TOP VIEW)



SN54ALS244C, SN54AS244A . . . FK PACKAGE  
(TOP VIEW)



FUNCTION TABLE  
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

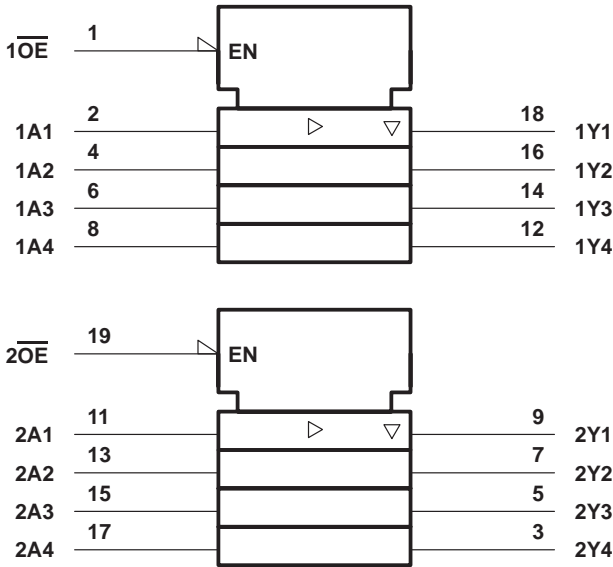
# SN54ALS244C, SN54AS244A, SN74ALS244C, SN74AS244A

## OCTAL BUFFERS AND LINE DRIVERS

### WITH 3-STATE OUTPUTS

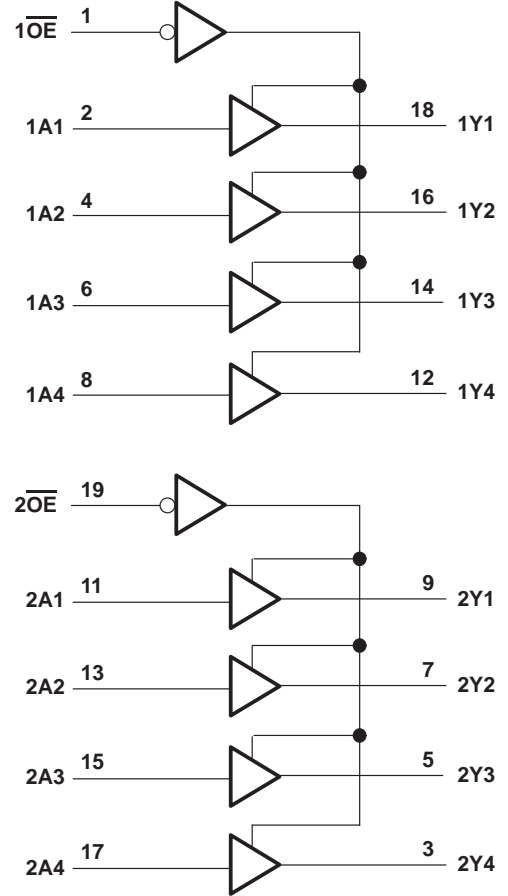
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#### logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### logic diagram (positive logic)



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, $V_{CC}$	7 V
Input voltage, $V_I$	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, $T_A$ : SN54ALS244C	-55°C to 125°C
SN74ALS244C	0°C to 70°C
Storage temperature range	-65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

# SN54ALS244C, SN54AS244A, SN74ALS244C, SN74AS244A

## OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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### recommended operating conditions

		SN54ALS244C			SN74ALS244C			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$	High-level input voltage	2			2			V
$V_{IL}$	Low-level input voltage	0.8†			0.8			V
		0.7‡						
$I_{OH}$	High-level output current	-12			-15			mA
$I_{OL}$	Low-level output current	12			24			mA
					48§			
$T_A$	Operating free-air temperature	-55			125			°C

† Applies over temperature range -55°C to 70°C

‡ Applies over temperature range 70°C to 125°C

§ Applies only to the -1 version and only if  $V_{CC}$  is between 4.75 V and 5.25 V

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54ALS244C			SN74ALS244C			UNIT	
			MIN	TYP†	MAX	MIN	TYP†	MAX		
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ ,	$I_I = -18\text{ mA}$	-1.5			-1.5			V	
$V_{OH}$	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	$I_{OH} = -0.4\text{ mA}$	$V_{CC} - 2$			$V_{CC} - 2$			V	
		$I_{OH} = -3\text{ mA}$	2.4	3.2	2.4	3.2				
	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -12\text{ mA}$	2							
		$I_{OH} = -15\text{ mA}$				2				
$V_{OL}$	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 12\text{ mA}$	0.25		0.4		0.25		V	
		$I_{OL} = 24\text{ mA}$					0.35			
		$I_{OL} = 48\text{ mA (-1 version)}$					0.35			
$I_{OZH}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 2.7\text{ V}$	20			20			μA	
$I_{OZL}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 0.4\text{ V}$	-20			-20			μA	
$I_I$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 7\text{ V}$	0.1			0.1			mA	
$I_{IH}$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 2.7\text{ V}$	20			20			μA	
$I_{IL}$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 0.4\text{ V}$	-0.1			-0.1			mA	
$I_{O\#}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 2.25\text{ V}$	-20		-112		-30		-112	mA
$I_{CC}$	$V_{CC} = 5.5\text{ V}$	Outputs high	9		18		9		17	mA
		Outputs low	15		25		15		24	
		Outputs disabled	17		29		17		27	

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

# The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .

# SN54ALS244C, SN54AS244A, SN74ALS244C, SN74AS244A

## OCTAL BUFFERS AND LINE DRIVERS

### WITH 3-STATE OUTPUTS

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#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>1</sub> = 500 Ω, R <sub>2</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX†				UNIT
			SN54ALS244C		SN74ALS244C		
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A	Y	1	16	2	10	ns
t <sub>PHL</sub>			3	12	3	10	
t <sub>PZH</sub>	$\overline{\text{OE}}$	Y	1	26	3	20	ns
t <sub>PZL</sub>			1	24	3	20	
t <sub>PHZ</sub>	$\overline{\text{OE}}$	Y	2	10	2	10	ns
t <sub>PLZ</sub>			1	26	1	13	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T <sub>A</sub> : SN54AS244A	–55°C to 125°C
SN74AS244A	0°C to 70°C
Storage temperature range	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		SN54AS244A			SN74AS244A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage			0.8			0.8	V
I <sub>OH</sub>	High-level output current			–12			–15	mA
I <sub>OL</sub>	Low-level output current			48			64	mA
T <sub>A</sub>	Operating free-air temperature	–55		125	0		70	°C



# SN54ALS244C, SN54AS244A, SN74ALS244C, SN74AS244A

## OCTAL BUFFERS AND LINE DRIVERS

### WITH 3-STATE OUTPUTS

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		SN54AS244A		SN74AS244A		UNIT	
			MIN	TYP†	MAX	MIN		TYP†
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ ,	$I_I = -18\text{ mA}$			-1.2		-1.2	V
$V_{OH}$	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ ,	$I_{OH} = -2\text{ mA}$	$V_{CC} - 2$		$V_{CC} - 2$		V	
	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -3\text{ mA}$	2.4	3.4	2.4	3.4		
		$I_{OH} = -12\text{ mA}$	2.4					
		$I_{OH} = -15\text{ mA}$			2.4			
$V_{OL}$	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 48\text{ mA}$		0.55			V	
		$I_{OL} = 64\text{ mA}$				0.55		
$I_{OZH}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 2.7\text{ V}$		50		50	$\mu\text{A}$	
$I_{OZL}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 0.4\text{ V}$		-50		-50	$\mu\text{A}$	
$I_I$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 7\text{ V}$		0.1		0.1	mA	
$I_{IH}$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 2.7\text{ V}$		20		20	$\mu\text{A}$	
$I_{IL}$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 0.4\text{ V}$		-0.5		-0.5	mA	
				-1		-1		
$I_{O\ddagger}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 2.25\text{ V}$	-50	-150	-50	-150	mA	
$I_{CC}$	$V_{CC} = 5.5\text{ V}$	Outputs high	22	34	22	34	mA	
		Outputs low	60	90	60	90		
		Outputs disabled	34	54	34	54		

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .

### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ , $C_L = 50\text{ pF}$ , $R_1 = 500\ \Omega$ , $R_2 = 500\ \Omega$ , $T_A = \text{MIN to MAX}\S$				UNIT
			SN54AS244A		SN74AS244A		
			MIN	MAX	MIN	MAX	
$t_{PLH}$	A	Y	2	9	2	6.2	ns
$t_{PHL}$			1	7	1	6.2	
$t_{PZH}$	$\overline{OE}$	Y	1	10	1	9	ns
$t_{PZL}$			2	8	2	7.5	
$t_{PHZ}$	$\overline{OE}$	Y	1	6.5	1	6	ns
$t_{PLZ}$			1	10.5	1	9	

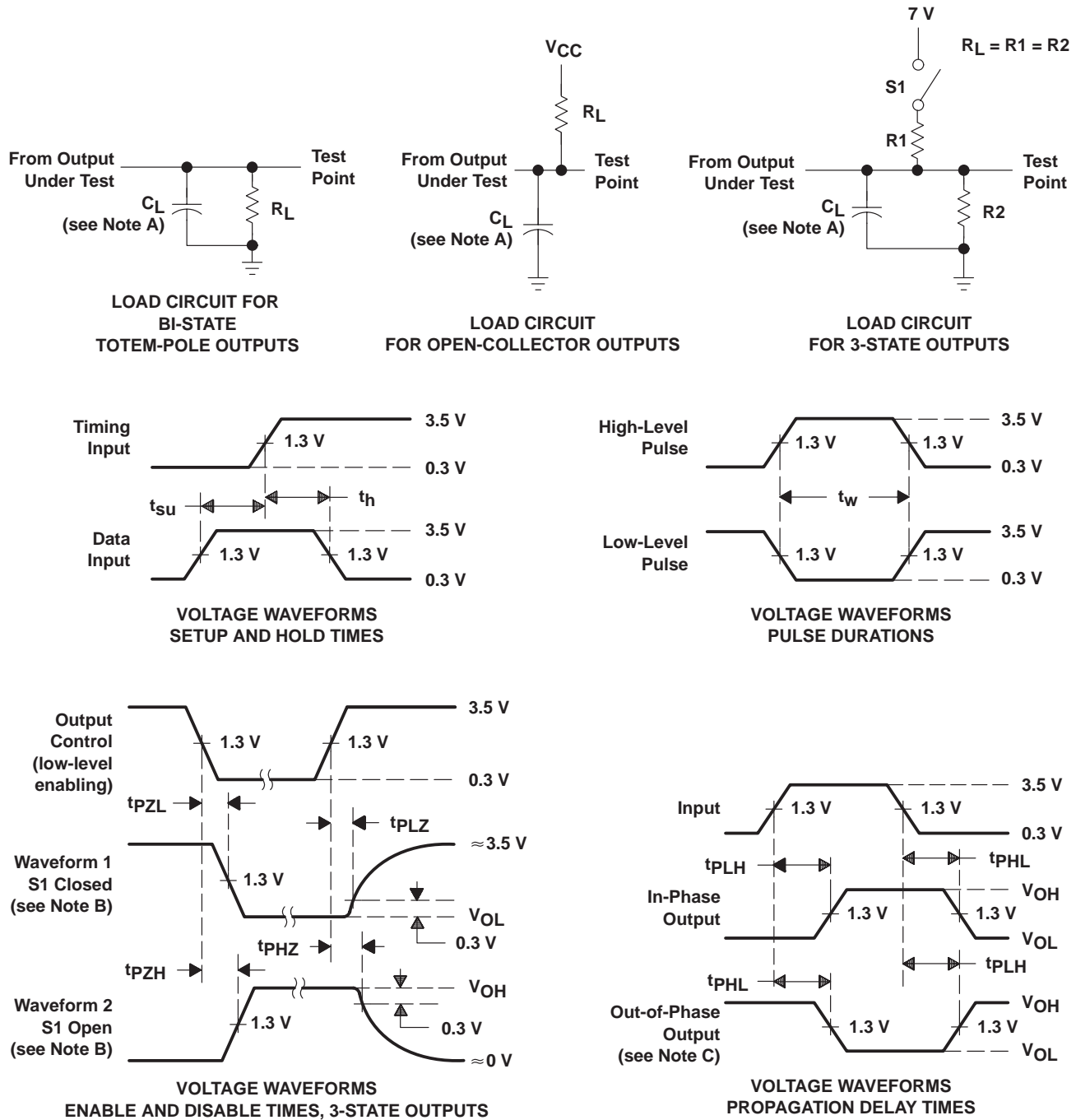
§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



# SN54ALS244C, SN54AS244A, SN74ALS244C, SN74AS244A OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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## PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.  
 D. All input pulses have the following characteristics:  $PRR \leq 1$  MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.  
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
5962-86839012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-8683901RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Call TI	
5962-8683901SA	ACTIVE	CFP	W	20	1	TBD	Call TI	Call TI	
5962-8683901VRA	ACTIVE	CDIP	J	20	20	TBD	A42	N / A for Pkg Type	
5962-8683901VSA	ACTIVE	CFP	W	20	25	TBD	Call TI	N / A for Pkg Type	
5962-9755901Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-9755901QRA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Call TI	
5962-9755901QSA	ACTIVE	CFP	W	20	1	TBD	Call TI	Call TI	
JM38510/38303B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/38303BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
M38510/38303B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/38303BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SN54ALS244CJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SN54AS244AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SN74ALS244C-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244C-1DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244C-1DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244C-1DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244C-1DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244C-1DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244C-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS244C-1NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS244C-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244C-1NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN74ALS244C-1NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244CDBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	
SN74ALS244CDBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244CDBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244CDBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244CDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244CDWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244CDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244CDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244CDWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244CDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244CN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS244CNE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS244CNSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244CNSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS244CNSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS244ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS244ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS244ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN74AS244ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS244ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS244ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS244AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS244ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS244ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS244ANSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS244ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54ALS244CFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54ALS244CJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SNJ54ALS244CW	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	
SNJ54AS244AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54AS244AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SNJ54AS244AW	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**OTHER QUALIFIED VERSIONS OF SN54ALS244C, SN54ALS244C-SP, SN54AS244A, SN74ALS244C, SN74AS244A :**

● Catalog: [SN74ALS244C](#), [SN54ALS244C](#), [SN74AS244A](#)

● Military: [SN54ALS244C](#), [SN54AS244A](#)

● Space: [SN54ALS244C-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS244C-1DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS244C-1NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74ALS244CDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ALS244CDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS244CNSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74AS244ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74AS244ANSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS244C-1DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS244C-1NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ALS244CDBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74ALS244CDWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS244CNSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AS244ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74AS244ANSR	SO	NS	20	2000	367.0	367.0	45.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

DW (R-PDSO-G20)

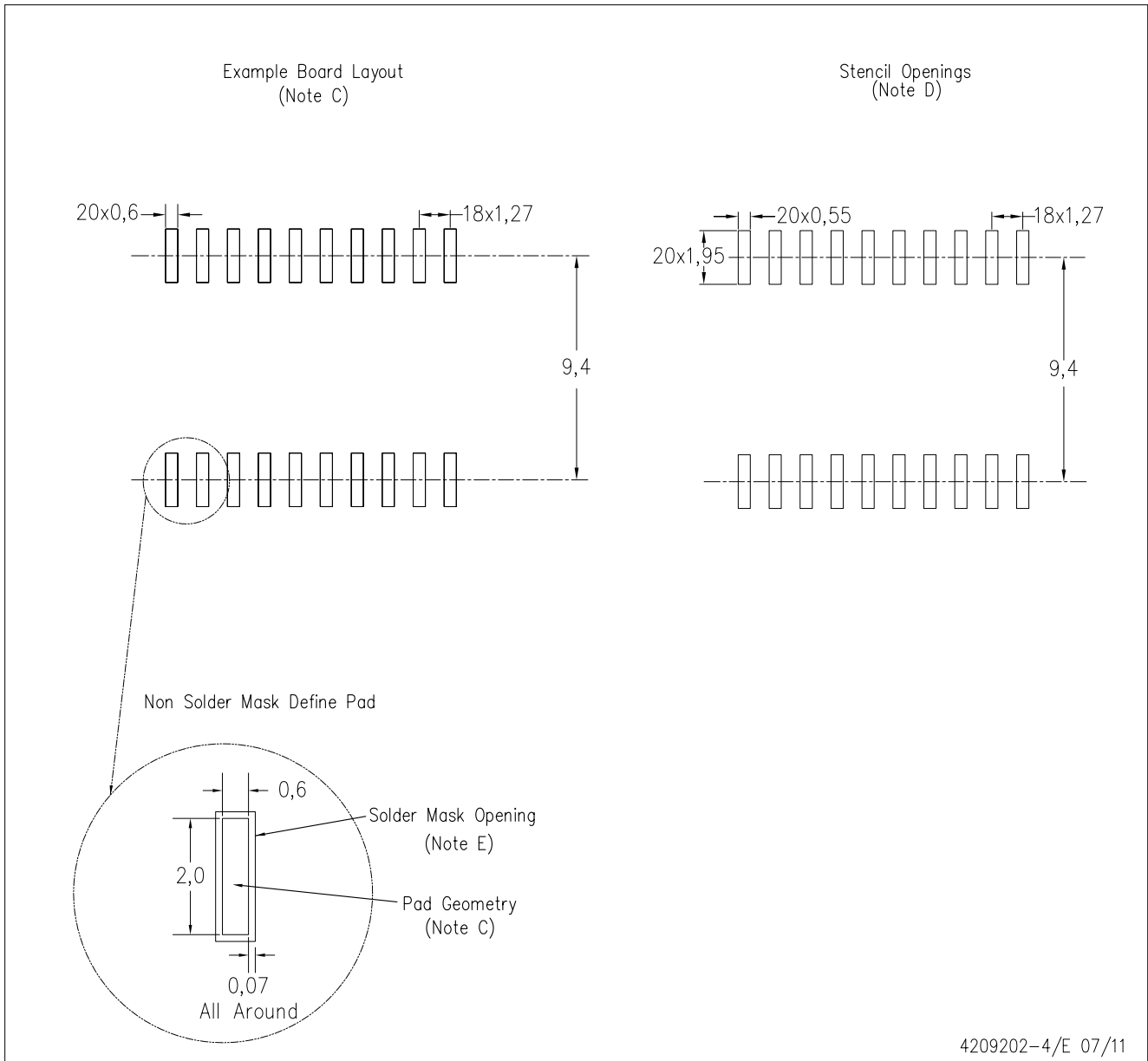
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



4209202-4/E 07/11

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

4040065 /E 12/01

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